



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20120817000
Die and Data Sheet Revision for DAC8562 Devices
Change Notification / Sample Request

Date: 8/24/2012
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI's standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services
Phone: +1(214) 480-6037
Fax: +1(214) 480-6659

20120817000
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
DAC7562SDGST	null
DAC7562SDSCT	null
DAC7563SDGST	null
DAC7563SDSCT	null
DAC8162SDGST	null
DAC8162SDSCT	null
DAC8163SDGST	null
DAC8163SDSCT	null
DAC8562SDGST	null
DAC8562SDSCT	null
DAC8563SDGST	null
DAC8563SDSCT	null

Technical details of this Product Change follow on the next page(s).




PCN Number:	20120817000		PCN Date:	08/24/2012							
Title:	Die and Data Sheet Revision for DAC8562 Devices										
Customer Contact:	PCN Manager	Phone:	+1(214)480-6037	Dept:	Quality Services						
Proposed 1st Ship Date:	11/24/2012	Estimated Sample Availability:		Date provided at sample request							
Change Type:											
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Assembly Materials						
<input checked="" type="checkbox"/>	Design	<input checked="" type="checkbox"/>	Electrical Specification	<input type="checkbox"/>	Mechanical Specification						
<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process						
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material	<input type="checkbox"/>	Wafer Bump Process						
<input type="checkbox"/>	Wafer Fab Site	<input type="checkbox"/>	Wafer Fab Materials	<input type="checkbox"/>	Wafer Fab Process						
PCN Details											
Description of Change:											
<p>This notification is to inform of a die and datasheet revision for DAC8562 devices. With revision C, OTP will no longer become corrupted during specific brown out events.</p> <p>Datasheet Revision:</p> <table border="1"> <thead> <tr> <th>Device Family</th> <th>Change From:</th> <th>Change To:</th> </tr> </thead> <tbody> <tr> <td>DAC8562</td> <td>SLAS719C</td> <td>SLAS719D</td> </tr> </tbody> </table> <p>The updated datasheet can be accessed by the following link: http://www.ti.com/general/docs/lit/getliterature.tsp?baseLiteratureNumber=SLAS719&fileType=pdf</p>						Device Family	Change From:	Change To:	DAC8562	SLAS719C	SLAS719D
Device Family	Change From:	Change To:									
DAC8562	SLAS719C	SLAS719D									
REVISION HISTORY											
Changes from Revision C (June 2011, first official release) to Revision D					Page						
• Replaced text "QFN" with "SON" (name change only, package/orderable did not change)					1						
• Typical power-down current consumption changed from 10 nA to 550 nA.					1						
• Changed power requirements specifications					5						
• Power-down current vs Temperature typical characteristic plot updated, AV _{DD} = 5.5 V					15						
• Power-down current vs Power-supply voltage typical characteristic plot updated					15						
• Power-down current vs Temperature typical characteristic plot updated, AV _{DD} = 2.7 V					23						
• Added Power-On Reset (POR) Levels section					30						
Reason for Change:											
To improve device performance and prevent brown out events.											
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):											
None.											

Changes to product identification resulting from this PCN:

Die Rev designator will change as shown in table & sample label below:

Current	New
Die Rev [2P] B	Die Rev [2P] C

Sample product shipping label to indicate die rev location (**not actual product label**)

 <p>TEXAS INSTRUMENTS MADE IN: Malaysia ZDC: 2Q:</p>			<p>(1P) SN74LS07NSR (Q) 2000 (D) 0336 (31T) LOT: 3959047MLA (4W) TKY(1T) 7523483SI2 (P) (2P) REV: (V) 0033317 (20L) CS0: SHE (21L) CC0: USA (22L) AS0: MLA (23L) AC0: MYS</p>				
<table border="1"> <tr> <td>MSL '2 /260C/1 YEAR</td> <td>SEAL DT</td> </tr> <tr> <td>MSL 1 /235C/UNLIM</td> <td>03/29/04</td> </tr> </table> <p>OPT: ITEM: 39 LBL: 5A (L)T0:1750</p>	MSL '2 /260C/1 YEAR	SEAL DT	MSL 1 /235C/UNLIM	03/29/04			
MSL '2 /260C/1 YEAR	SEAL DT						
MSL 1 /235C/UNLIM	03/29/04						

Product Affected:

DAC7562SDGSR	DAC7563SDSCR	DAC8163SDGSR	DAC8562SDSCR
DAC7562SDGST	DAC7563SDSCT	DAC8163SDGST	DAC8562SDSCT
DAC7562SDSCR	DAC8162SDGSR	DAC8163SDSCR	DAC8563SDGSR
DAC7562SDSCT	DAC8162SDGST	DAC8163SDSCT	DAC8563SDGST
DAC7563SDGSR	DAC8162SDSCR	DAC8562SDGSR	DAC8563SDSCR
DAC7563SDGST	DAC8162SDSCT	DAC8562SDGST	DAC8563SDSCT

Qualification Data: Approved 08/10/2012

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Qual Vehicle: DAC8562SDGSR

Die Construction Details

Wafer Fab Site:	DM5	Metallization:	Al0.5%Cu
Wafer Fab Process:	50HPA07	# Pins-Designator, Family:	10-DGS, MSOP
Assembly Site:	NS2		

Qualification: Plan Test Results

Reliability Test	Conditions	Sample Size/Fail
Electrical Characterization	Full Temperature	Pass
ESD - CDM	250 V/1-3	3/0

Qual Vehicle: DAC8562SDSCR			
Die Construction Details			
Wafer Fab Site:	DM5	Metallization:	Al0.5%Cu
Wafer Fab Process:	50HPA07	# Pins-Designator, Family:	10-DSC, SON
Assembly Site:	MLA		
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results			
Reliability Test	Conditions		Sample Size/Fail
Electrical Characterization	Full Temperature		Pass
ESD - HBM	1000 V/4-6		3/0
ESD - CDM	250 V/16-18		3/0
Latch-up	QSS009-004/-		6/0

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or to your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com